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(54) **SWITCHING OSCILLATION REDUCTION
FOR POWER SEMICONDUCTOR DEVICE
MODULES**

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(57) **ABSTRACT**

In a general aspect, a half-bridge circuit includes a substrate having first, second and third patterned metal layers disposed on a surface. The circuit also includes first and second high-side transistors disposed on the first patterned metal layer, and first and conductive clips electrically coupling, respectively, the first and second high-side transistors with the second patterned metal layer. The circuit also includes first and second low-side transistors disposed on the second patterned metal layer, and third and fourth conductive clips electrically coupling, respectively, the first and second low-side transistors with the third patterned metal layer. The circuit further includes a DC+ terminal electrically coupled with the first patterned metal layer via a first conductive post disposed between the first and second high-side transistors, and a DC- terminal electrically coupled with the third patterned metal layer via a second conductive post disposed between the third and fourth conductive clips.

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